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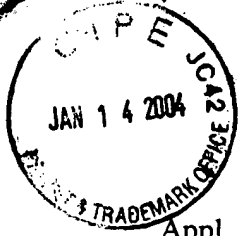
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RESPONSE UNDER 37 C.F.R. 1.116 -  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2829  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/099,641  
Applicants: : Wilbur G. Catabay and Richard Schinella  
Filed: : March 15, 2002  
Title : LOW K DIELECTRIC COMPOSITE LAYER FOR INTEGRATED  
CIRCUIT STRUCTURE WHICH PROVIDES VOID-FREE LOW K  
DIELECTRIC MATERIAL BETWEEN METAL LINES WHILE  
MITIGATING VIA POISONING  
Grp./ A.U. : 2829  
Examiner : Lisa A. Kilday  
Docket No. : 99-102/1D

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450	
on	<u>September 16, 2003</u> (Date of Deposit)
John P. Taylor, Reg. No. 22,369	
	<u>John P. Taylor</u> Signature
	<u>September 16, 2003</u> Date of Signature

RESPONSE TO FINAL REJECTION

Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: September 16, 2003

Sir:

In response to the Final Rejection mailed July 16, 2003, please amend the application as follows:

01/16/2004 EFLORES 00000113 122252 10099641

02 FC:1251 110.00 DA



### REMARKS CONCERNING EXTENSION FEE

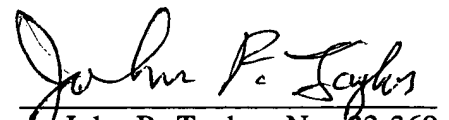
It is believed by Applicants that only a *fourth* month extension fee should be needed since on September 16, 2003 (as indicated on the enclosed copy of page one containing Applicants' Certificate of Mailing dated September 16th), Applicants mailed to the USPTO their response to the Final Rejection (mailed by the USPTO on July 16, 2003). That is, Applicants mailed their response to the USPTO within *two* months of the mailing date of the Final Rejection.

Applicants also enclose a copy of their stamped postcard receipt which accompanied Applicants' September 16th response to the Final Rejection. The USPTO date stamped on the postcard a receipt date of "*Sep 22 2003*" as seen in the further enclosure. Since September 20 and 21 of 2003 respectively fell on Saturday and Sunday that year, and since it is the practice of Applicants' Attorney's law practice to deposit the mail at the end of the day, it is not unreasonable to expect six days between Applicants' September 16th mailing date in California and the September 22nd receipt date in Virginia.

It is noted that the comments on the Advisory Action mailed by the USPTO on 12/31/03 state that Applicants' response was received "*22 October 2003*". The attached postcard clearly indicates the receipt date should have been stated in the Advisory Action as "*22 September 2003*" *not* "*22 October 2003*". This would be consistent with the information stamped by the USPTO on the postcard receipt.

Therefore, the authorization of payment for a fourth month extension fee in the amount of One Hundred Ten Dollars (\$110.00) is enclosed.

Respectfully Submitted,

  
John P. Taylor, No. 22,369  
Attorney for Applicants  
Telephone No. (909) 303-1416

RECEIVED SEP 29 2003

LSI Docket No. 99-102/1D

Serial No. 10/099,641

Filed: 3/15/2002

Inventors: Wilbur G. Catabay and Richard Schinella

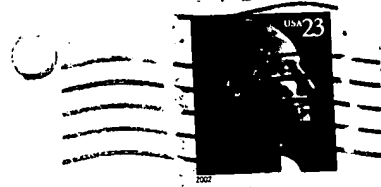
Title: LOW K DIELECTRIC COMPOSITE LAYER FOR INTEGRATED CIRCUIT  
STRUCTURE WHICH PROVIDES VOID-FREE LOW K DIELECTRIC  
MATERIAL BETWEEN METAL LINES WHILE MITIGATING VIA  
POISONING

Honorable Commissioner:

Please acknowledge receipt of the following document:

X "Response to Final Rejection" dated September 16, 2003.

Please date stamp received and deposit in U.S. Mail.



JOHN P. TAYLOR  
PATENT ATTORNEY  
P O BOX 1598  
TEMECULA CA 92593-1598





RECEIVED SEP 29 2003

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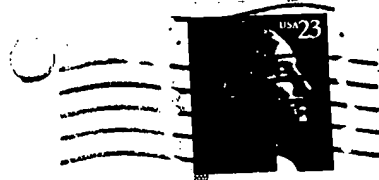
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